



(19)

(11) Publication number:

**06151653 A**

Generated Document.

## PATENT ABSTRACTS OF JAPAN

(21) Application number: **04305231**

(51) Intl. Cl.: **H01L 23/29 H01L 23/31**

(22) Application date: **16.11.92**

(30) Priority:

(43) Date of application  
publication: **31.05.94**

(84) Designated contracting  
states:

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### (54) STRUCTURE AND METHOD FOR SEALING TEMPERATURE SENSOR

(57) Abstract:

**PURPOSE:** To provide a construction and method for sealing a thermosensor which facilitate the significant improvement of the productivity and the reliability.

**CONSTITUTION:** A primary sealing part 7 made of resin is applied over a thermistor element 1 for a temperature sensor, its lead wires 2, joint parts between the lead wires 2 and insulated wires 3 and the insulation coverings 3b of the insulated wires 3 by injection molding. A secondary sealing part 8 made of resin is applied to the surface of the primary sealing part 7 by injection molding. Protrusions 7a are provided on the surface of the primary sealing part 7 in order to support the injection molding of the secondary sealing part 8 and to prevent the primary sealing part 7 from movement at the time of the injection molding of the secondary sealing part 8. If PPS resin is employed as the injection molding material of the primary and secondary sealing parts, the primary sealing part and the secondary sealing part and the primary sealing part and the insulation coverings (polyvinyl chloride coverings) can adhere tightly to each other.

